

Is Now Part of



ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at www.onsemi.com

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, emplo



FCH190N65F_F085

N-Channel SuperFET II FRFET MOSFET **650 V, 20.6 A, 190 m**Ω

Features

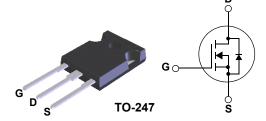
- Typical $R_{DS(on)}$ = 148 $m\Omega$ at V_{GS} = 10 V, I_D = 10 A
- Typical $Q_{q(tot)}$ = 63 nC at V_{GS} = 10V, I_D = 10 A
- UIS Capability
- Qualified to AEC Q101
- RoHS Compliant

Description

automotive.

SuperFET® II MOSFET is Fairchild Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently SuperFETII is very well suited for the Soft switching and Hard Switching topologies like High Voltage Full Bridge and Half Bridge DC-DC, Interleaved Boost PFC, Boost PFC for HEV-EV

SuperFET II FRFET® MOSFET's optimized body diode reverse recovery performance can remove additional component and improve system reliability.



For current package drawing, please refer to the Fairchild website at https://www.fairchildsemi.com/package-drawings/TO/ TO247A03.pdf

Application

- Automotive On Board Charger
- Automotive DC/DC converter for HEV



December 2014

Maximum Ratings $T_C = 25$ °C unless otherwise noted

Symbol	Paramete	er	Ratings	Units
V_{DSS}	Drain to Source Voltage		650	V
V_{GS}	Gate to Source Voltage		±20	V
	Drain Current - Continuous (V _{GS} =10) (No	ote 1)	20.6	Α
ID	Pulsed Drain Current		See Fig 4	Α
E _{AS}	Single Pulse Avalanche Rating	(Note 2)	400	mJ
al / alk	MOSFET dv/dt		100	1//
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	50	V/ns
1	Power Dissipation		208	W
P_D	Derate Above 25°C		1.67	W/°C
T _J , T _{STG}	Operating and Storage Temperature		-55 to + 150	°C
$R_{\theta JC}$	Maximum Thermal Resistance Junction to Case		0.6	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance Junction to	o Ambient (Note 4)	40	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FCH190N65F	FCH190N65F_F085	TO-247	-	-	30

Notes:

- 1: Current is limited by bondwire configuration.
- 2: Starting T_J = 25°C, L = 50mH, I_{AS} = 4A, V_{DD} = 100V during inductor charging and V_{DD} = 0V during time in avalanche. 3: I_{SD} ≤ 10A, di/dt ≤ 200 A/us, V_{DD} ≤ 380V, starting T_J = 25°C.
- 4: R_{0,IA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design, while $R_{\theta JA}$ is determined by the board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

Units

Max

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

Parameter

Off Ch	Off Characteristics						
B _{VDSS}	Drain to Source Breakdown Voltage	I _D = 250μA, V	_{GS} = 0V	650	-	-	V
ı	Design to Course Lookens Current	V _{DS} =650V,	$T_J = 25^{\circ}C$	-	-	10	μΑ
IDSS	Drain to Source Leakage Current	$V_{GS} = 0V$	$T_J = 150^{\circ}C(Note 5)$	-	-	1	mA
IGSS	Gate to Source Leakage Current	$V_{GS} = \pm 20V$		-	_	±100	nA

Test Conditions

Min

Тур

On Characteristics

Symbol

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$		3.0	-	5.0	V
rps(on) Drain to Source On Resistance	I _D = 27A,	$T_J = 25^{\circ}C$	-	148	190	$m\Omega$	
r _{DS(on)}	IDS(on) Drain to Source On Resistance	$V_{GS} = 10V$	$T_J = 150^{\circ}C(Note 5)$	-	346	401	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	V 05V V 0V	-	2447	3181	pF
C _{oss}	Output Capacitance	V _{DS} = 25V, V _{GS} = 0V, f = 1MHz	-	2345	3048	pF
C _{rss}	Reverse Transfer Capacitance	1 - 111112	1	131	-	pF
R_g	Gate Resistance	f = 1MHz	1	0.5	-	Ω
$Q_{g(ToT)}$	Total Gate Charge		-	63	82	nC
$Q_{g(th)}$	Threshold Gate Charge	V _{DD} = 380V	-	4.3	5.6	nC
Q_{gs}	Gate to Source Gate Charge	I _D = 10A V _{GS} = 10V	-	12.6	-	nC
Q_{gd}	Gate to Drain "Miller" Charge	- G3 - 5 -	-	28	-	nC

Switching Characteristics

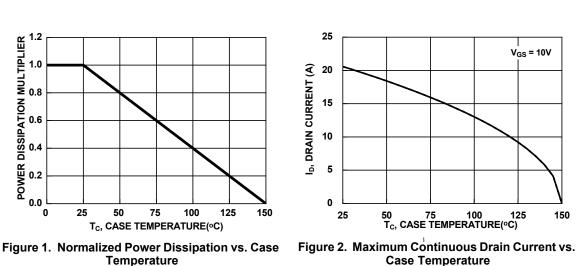
t _{on}	Turn-On Time		-	40	100	ns
t _{d(on)}	Turn-On Delay Time		-	25	-	ns
t _r	Rise Time	V _{DD} = 380V, I _D = 10A,	-	14.5	-	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10V, R_G = 4.7\Omega$	-	64	-	ns
t _f	Fall Time		-	5	-	ns
$t_{\rm off}$	Turn-Off Time		-	69	158	ns

Drain-Source Diode Characteristics

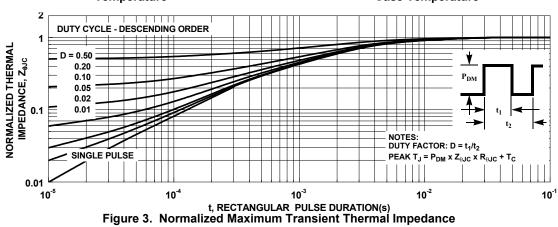
V_{SD}	Source to Drain Diode Voltage	I _{SD} = 10A, V _{GS} = 0V	-	-	1.2	V
T _{rr}	Reverse Recovery Time	$I_F = 10A$, $dI_{SD}/dt = 100A/\mu s$	1	141	1	ns
Q _{rr}	Reverse Recovery Charge	V _{DD} = 520V	-	889	-	nC

Notes

5: The maximum value is specified by design at T_J = 150°C. Product is not tested to this condition in production.



Typical Characteristics



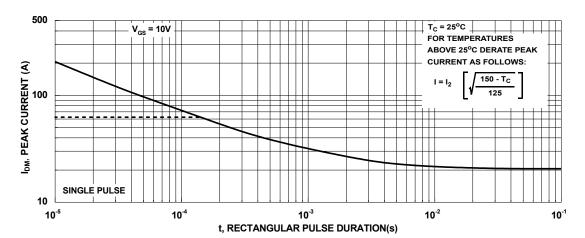


Figure 4. Peak Current Capability

Typical Characteristics

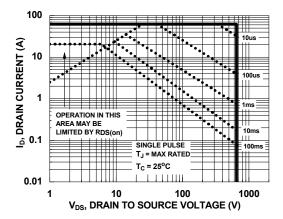


Figure 5. Forward Bias Safe Operating Area

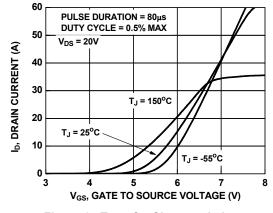


Figure 6. Transfer Characteristics

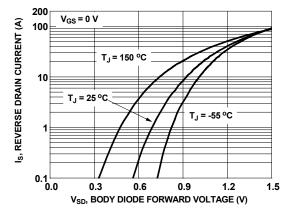


Figure 7. Forward Diode Characteristics

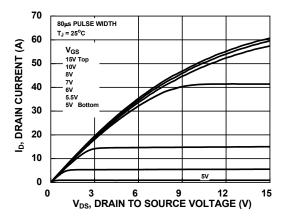


Figure 8. Saturation Characteristics

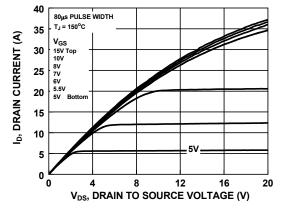


Figure 9. Saturation Characteristics

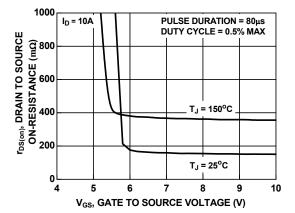


Figure 10. R_{DSON} vs. Gate Voltage

Typical Characteristics

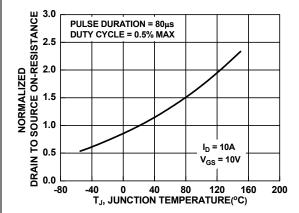


Figure 11. Normalized R_{DSON} vs. Junction Temperature

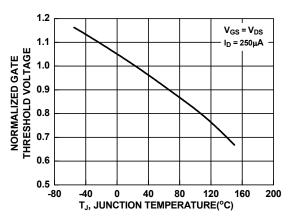


Figure 12. Normalized Gate Threshold Voltage vs.
Temperature

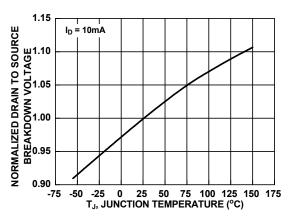


Figure 13. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

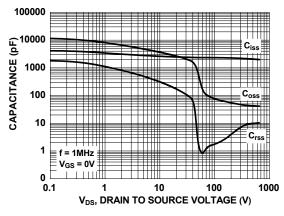


Figure 14. Capacitance vs. Drain to Source Voltage

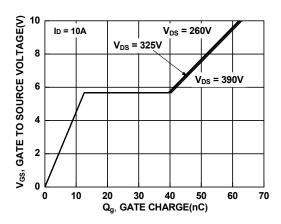


Figure 15. Gate Charge vs. Gate to Source Voltage

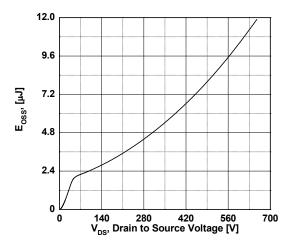


Figure 16. Eoss vs. Drain to Source Voltage

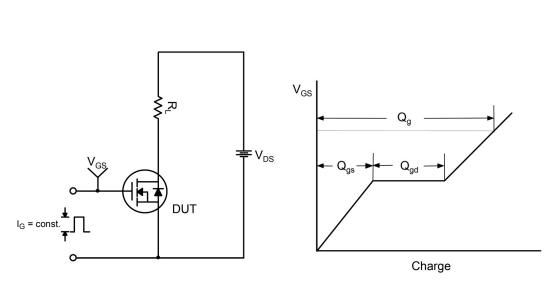


Figure 17. Gate Charge Test Circuit & Waveform

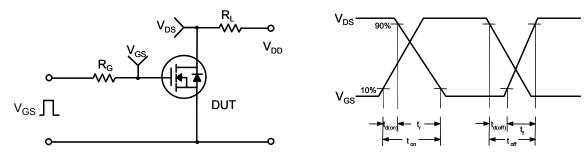


Figure 18. Resistive Switching Test Circuit & Waveforms

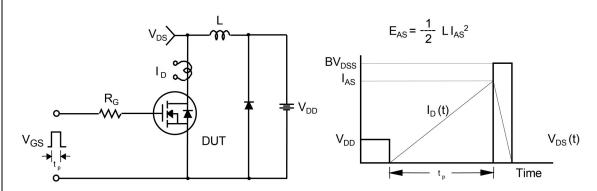
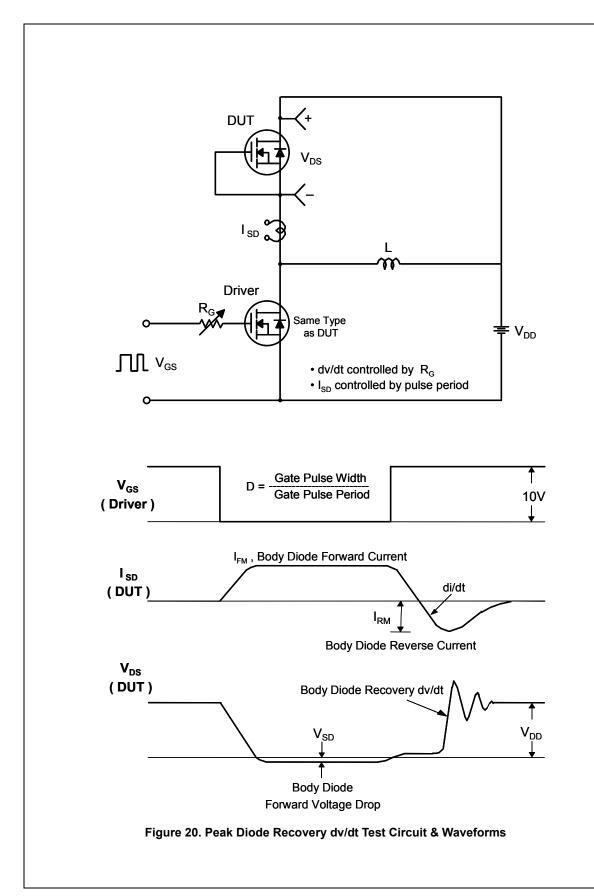


Figure 19. Unclamped Inductive Switching Test Circuit & Waveforms



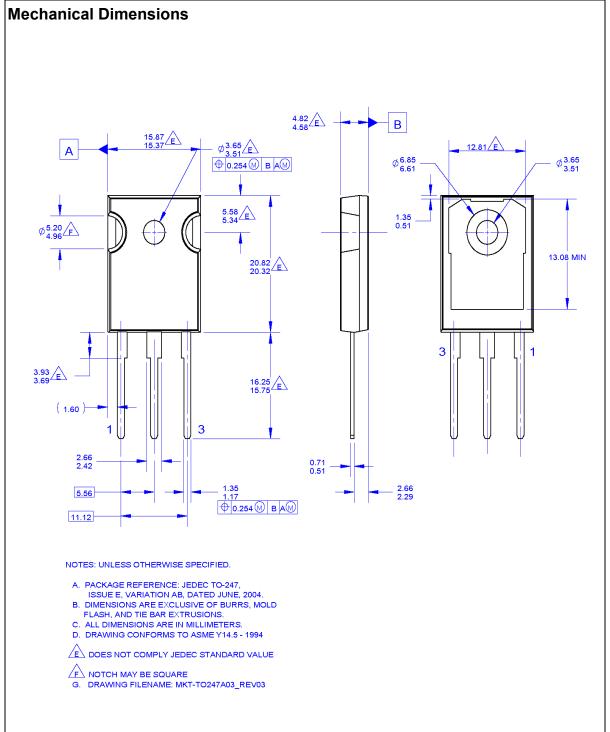


Figure 21. TO-247, Molded, 3-Lead, Jedec Variation AB

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

http://www.fairchildsemi.com/package-drawings/TO/TO247A03.pdf





Rev 173

TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

AccuPower™
AttitudeEngine™
Awinda®
AX-CAP®*
BitSiC™
Build it Now™
CorePLUS™

Build if Now ''''

CorePLUS™

CROSSVOLT™

CTL™

Current Transfer Logic™

DEUXPEED®
DEUXPEED®
Dual Cool™
EcoSPARK®
EfficentMax™
ESBC™

Fairchild[®]
Fairchild Semiconductor[®]
FACT Quiet Series™

FACT[®]
FAST[®]
FastvCore[™]
FETBench[™]
FPS[™]

F-PFS™ FRFET®

Global Power ResourceSM

GreenBridge™ Green FPS™

Green FPS™ e-Series™

Gmax™ GTO™ IntelliMAX™ ISOPLANAR™

Marking Small Speakers Sound Louder

and Better™ MegaBuck™ MICROCOUPLER™ MicroFET™

MicroPak[™] MicroPak2[™] MillerDrive[™] MotionMax[™]

MotionGrid®
MTi®
MTx®
MVN®
mWSaver®
OptoHiT™
OPTOLOGIC®

OPTOPLANAR®

©® PowerTrench® PowerXS™

Programmable Active Droop™

QFET[®] QS[™] Quiet Series[™] RapidConfigure[™]

Saving our world, 1mW/W/kW at a time™

SignalWise™ SmartMax™ SMART START™

Solutions for Your Success™

SPM[®]
STEALTH™
SuperFET[®]
SuperSOT™-3
SuperSOT™-6
SuperSOT™-8

SupreMOS[®]
SyncFET™
Sync-Lock™

SYSTEM ®*

TinyBoost®
TinyBuck®
TinyCalc™
TinyLogic®
TINYOPTO™
TinyPower™
TinyPWM™
TinyWire™

TranSiC™
TriFault Detect™
TRUECURRENT®*
uSerDes™

SerDes"
UHC®
UItra FRFET™
UniFET™
VCX™
VisualMax™
VoltagePlus™
XS™
Xsens™

仙童 ™

*Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. TO OBTAIN THE LATEST, MOST UP-TO-DATE DATASHEET AND PRODUCT INFORMATION, VISIT OUR WEBSITE AT http://www.fairchildsemi.com. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used here in:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.Fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufactures of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed application, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handing and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address and warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification Product Status		Definition
Advance Information Formative / In Design		Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdt/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and exp

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative